

U.S.S.N. 09/410,896

In The Abstract

Please amend the Abstract as follows:

A cooling stage for a semiconductor substrate and a method for utilizing such cooling stage for improved cooling of a semiconductor substrate. In the cooling stage, a pedestal that has a substantially planar top surface is equipped with a first plurality of circular grooves concentrically formed in the top surface and a second plurality of linear grooves formed in radial directions emanating from a center of the top surface in fluid communication with the first plurality of circular grooves to allow a cooling fluid to flow therethrough when a semiconductor substrate is positioned on the top surface of the stage.